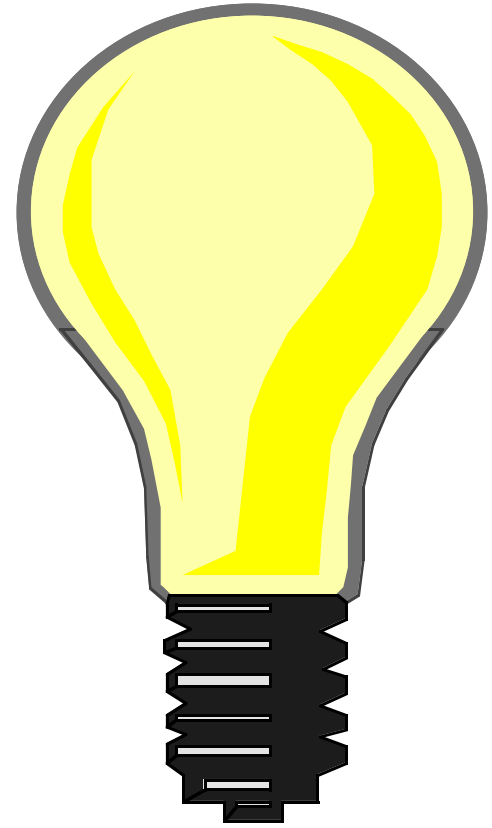




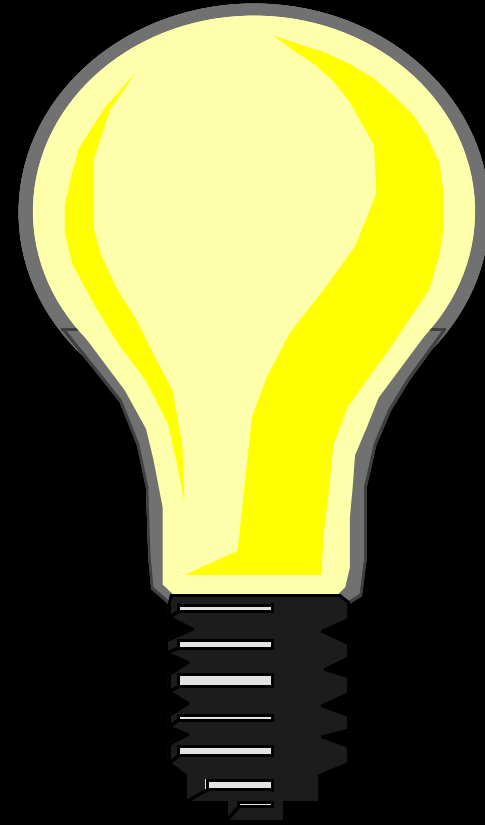
# When can we turn out the lights at Probe?

*Ron Leckie*

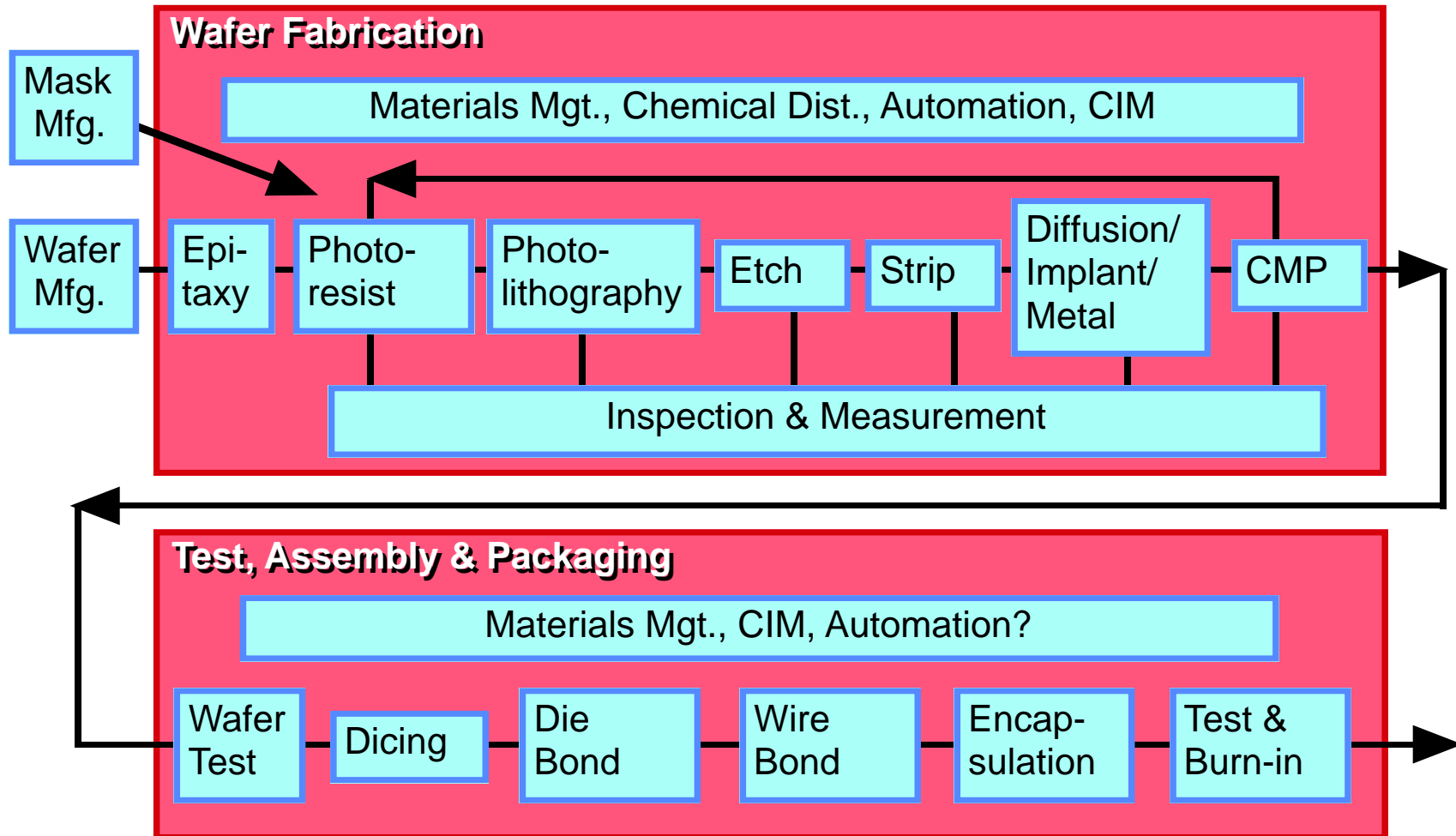


## Agenda:

- **Processes**
- **People**
- **Software**
- **Financial**
- **Equipment**
- **A Pro-Active Step**
- **Outlook**



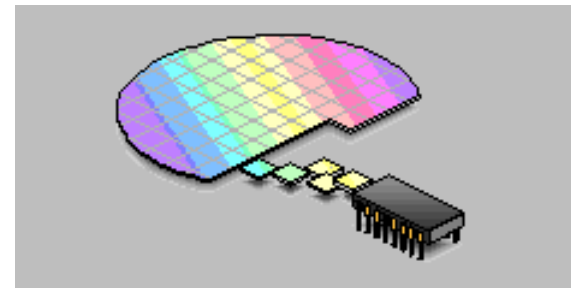
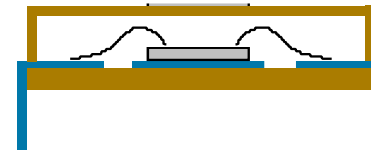
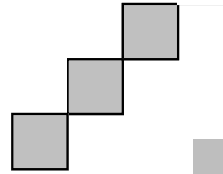
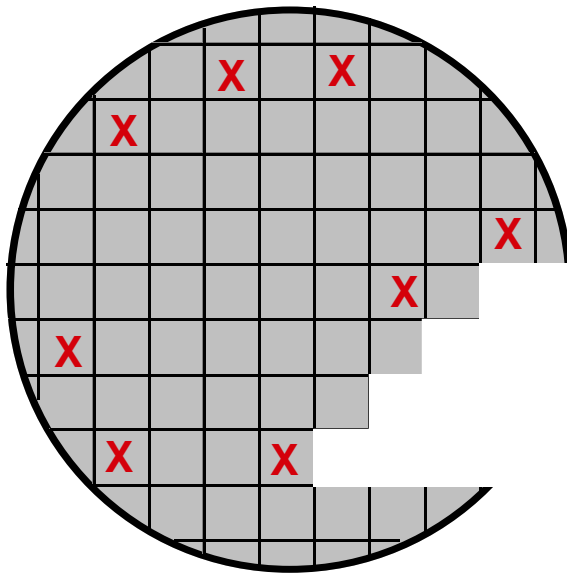
# Semiconductor Manufacturing



# The Flow

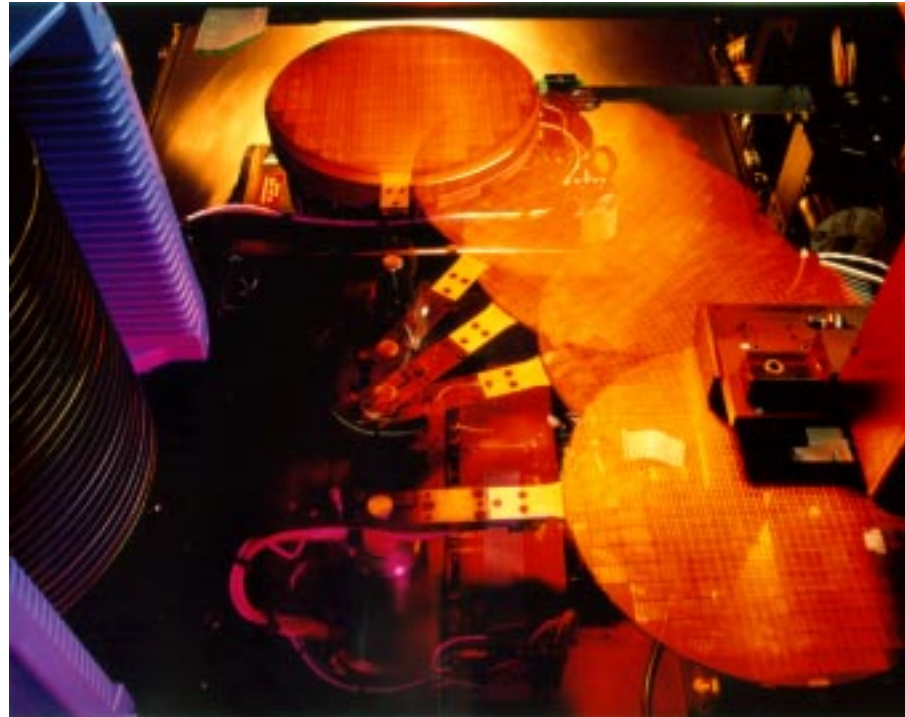
<u>Material</u>	<u>Mfg. Step</u>	<u>Treated as...</u>
Wafer	Wafer Fab	Process
Wafer	Wafer probe	Product
Wafer	Laser Repair	Product
Wafer	Mount & Scribe	Process
Wafer / Die	Dicing	Process
Frame	Die / Wire Bond	Process
Device	Packaging	Process
Device	Package Test / Burn-in	Product
Device	Finishing & Pack	Process

# Assembly & Packaging



# Process issues:

- Flow
- Location
- Cluster
- Inking
- Multiple Fab sources
- OCR / Wafer ID
- Probe Cleaning



# Human Factors / Management

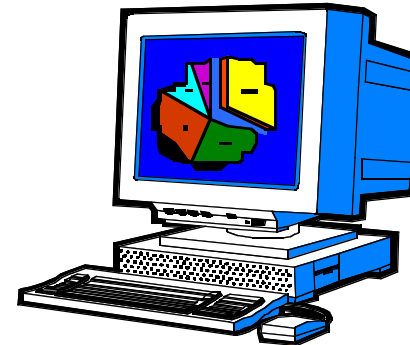
- **Batch Process vs. “Job Shop”**
- **Interrupt driven**
- **Strategic Vision?**
- **Industrial Engineering?**
- **Metrics**
- **ROI Analysis**





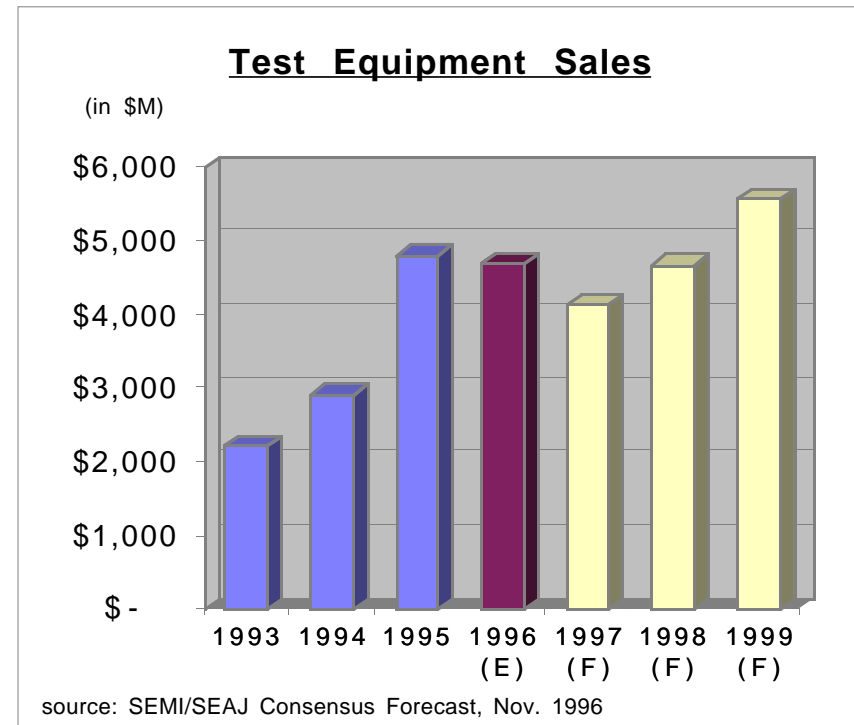
# Software

- **The Tasks:**
  - Equipment programming & set-up
  - Wafer Maps
  - Lot Data
  - Device Data
- **Not a major barrier!**
- **Technology is available!**
- **Takes attention to details!**



# Test Capital Spending

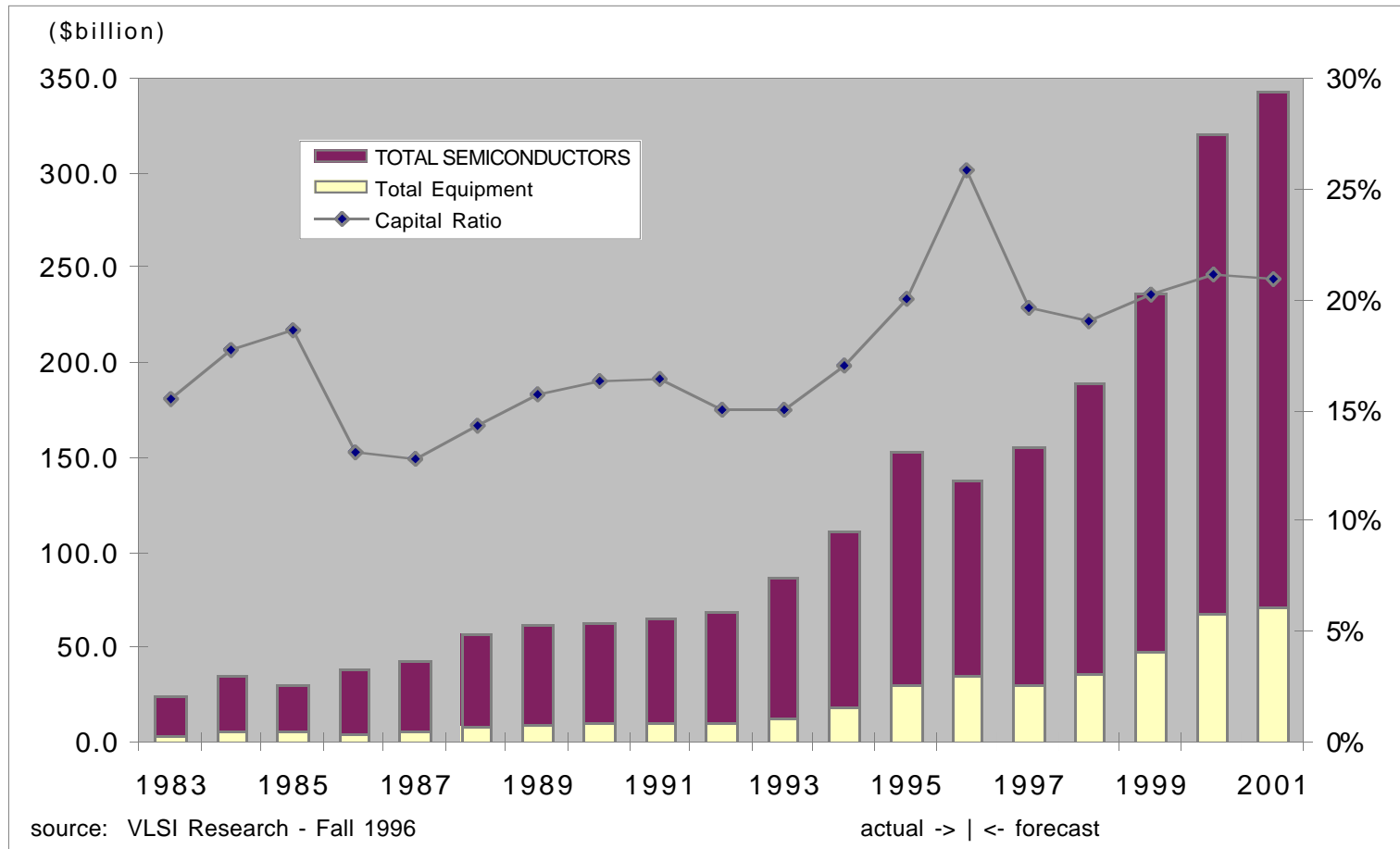
- Growth
- Over-Capacity
- Correction
- Recovery to Growth
- Driven by Unit Demand
- Short Equipment Leadtimes



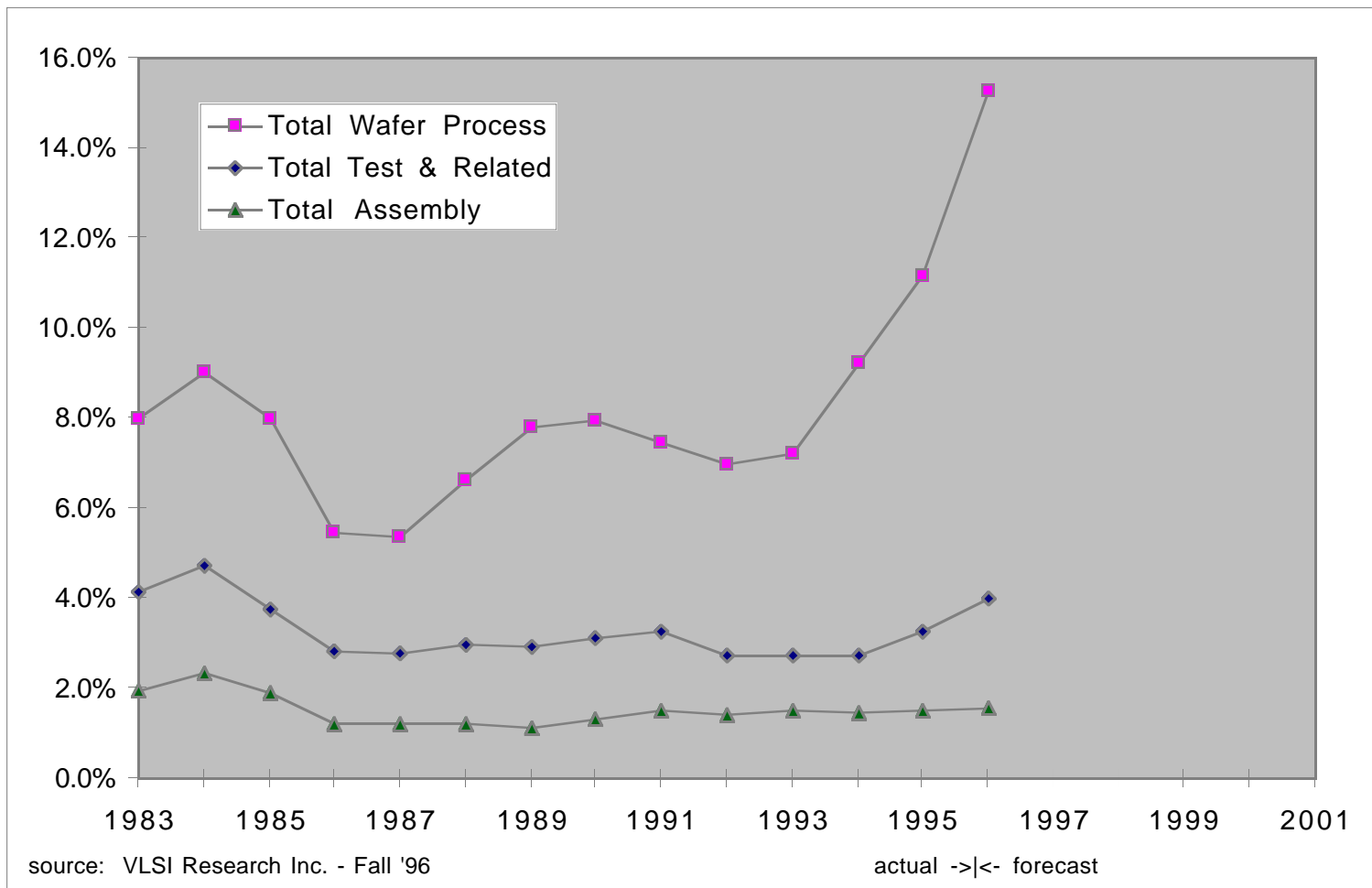
<u>ISS Forecasts:</u>	<u>1997</u>	<u>1998</u>	<u>1999</u>	<u>2000</u>	<u>2001</u>
SEMI	-12%	13%	19%	-	-
VLSI Res. Inc.	-12%	16%	27%	39%	4%

# Capital Spending Ratio

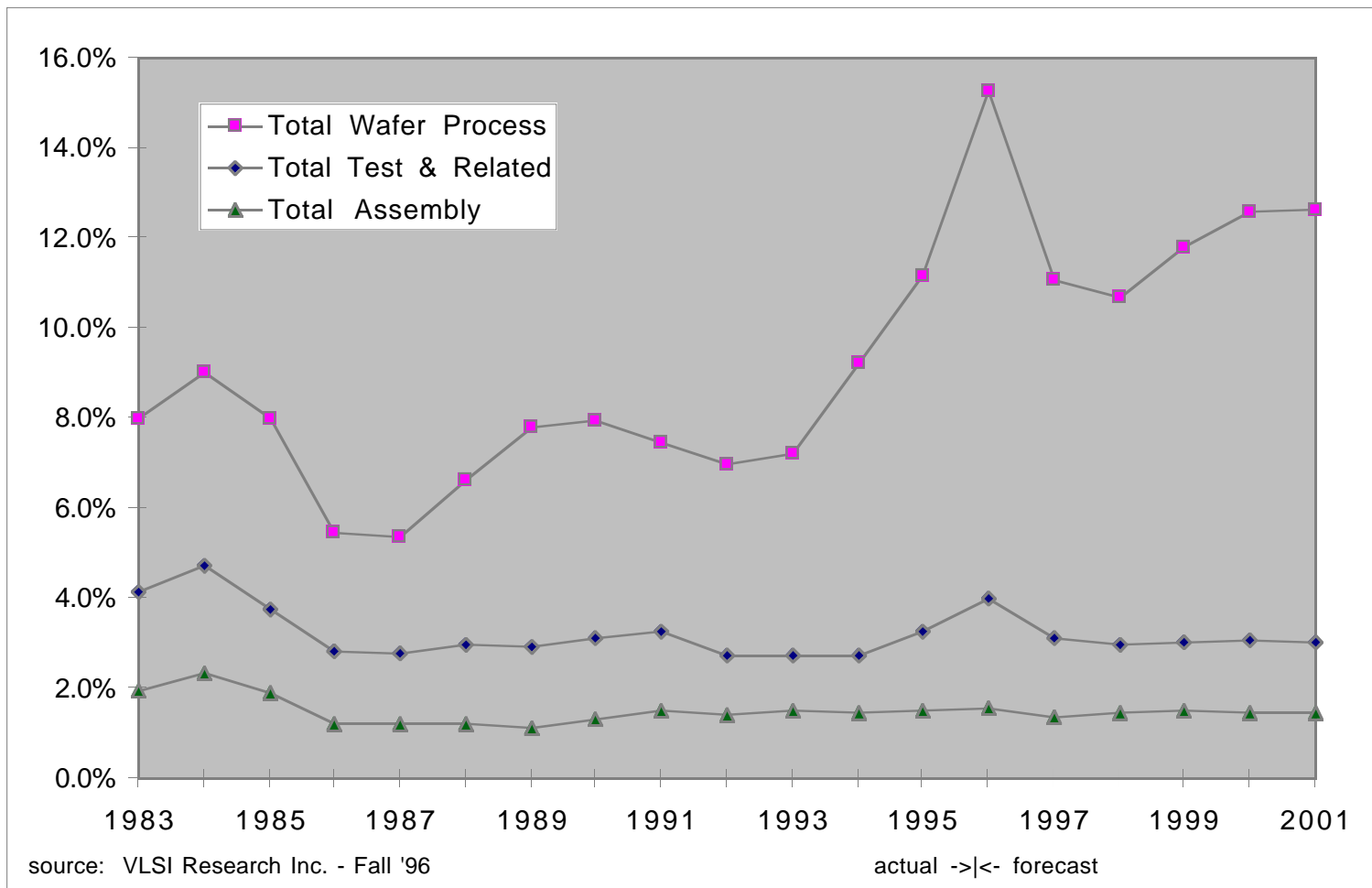
## All Semiconductor Equipment



# Capital Spending Ratio



# Capital Spending Ratio



# Automation ROI:

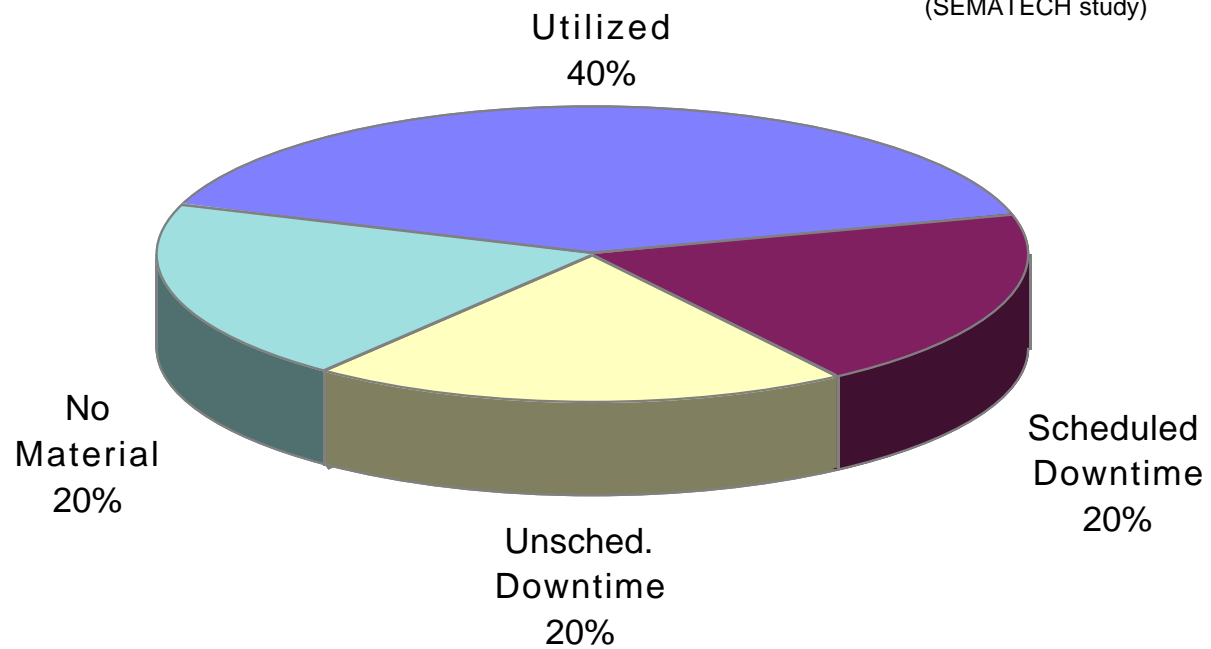
- Utilization
- Cycle Time
- Yield Improvement
- Human Errors
- Safety



# Equipment Utilization

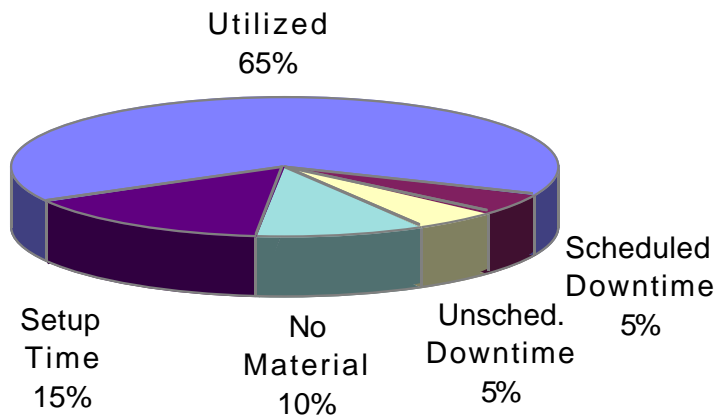
## Fab Equipment

(SEMATECH study)

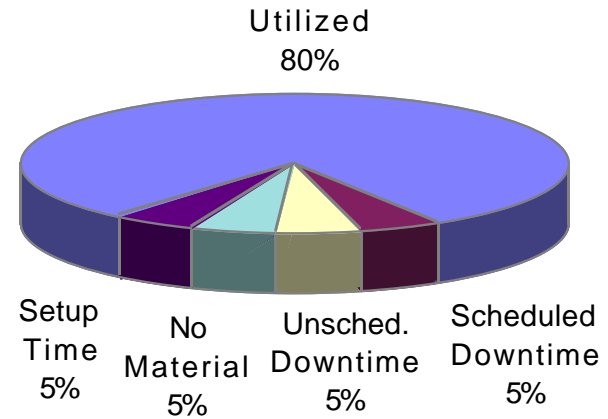


# Equipment Utilization

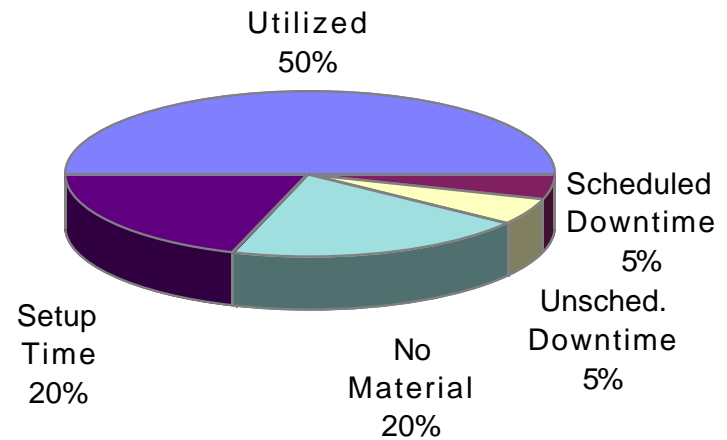
## Logic / MS Test



## Memory Test

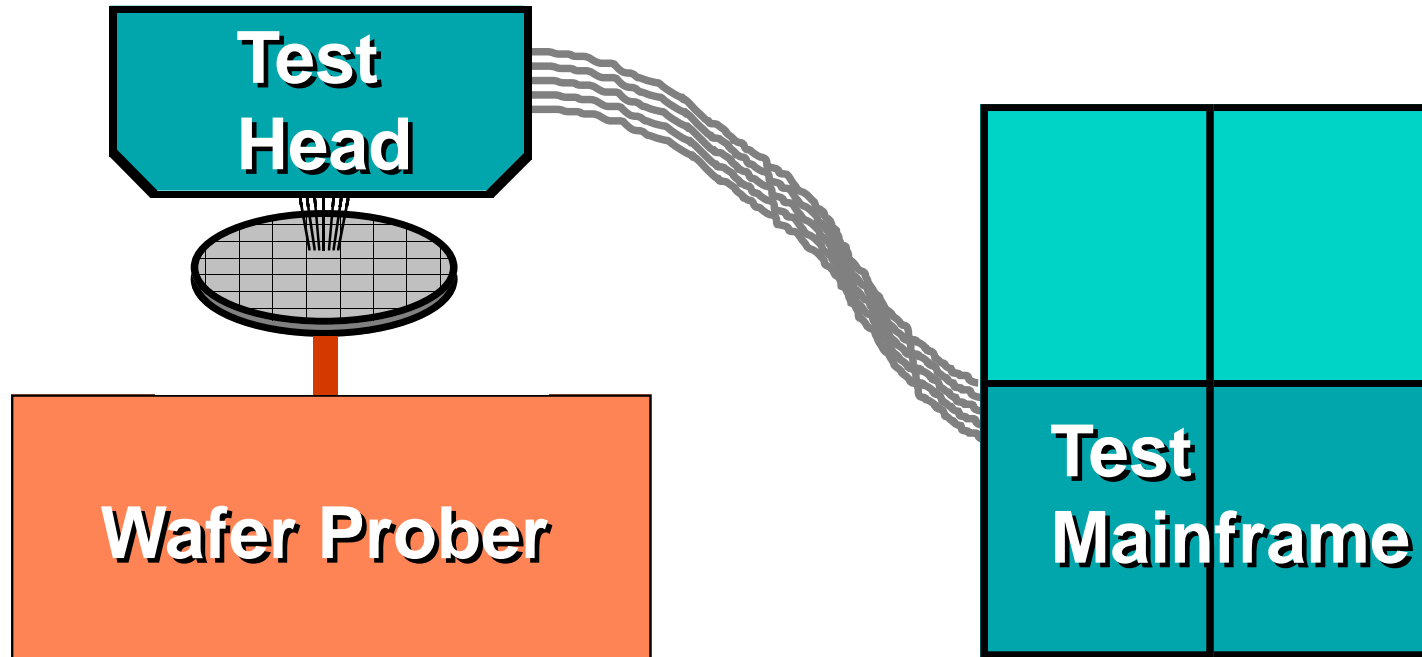


## ASIC Test





# Wafer Probe



Electroglas  
Tokyo Electron Ltd.  
Tokyo Seimitsu Co.

Advantest  
Credence  
Hewlett Packard  
LTX Corp.  
Schlumberger  
Teradyne

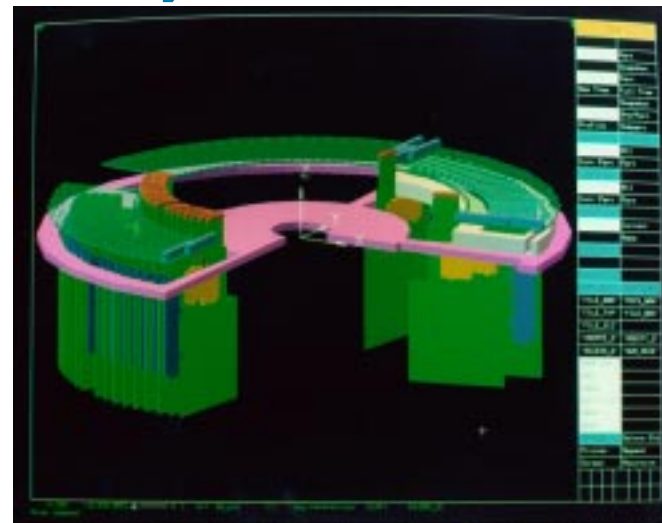
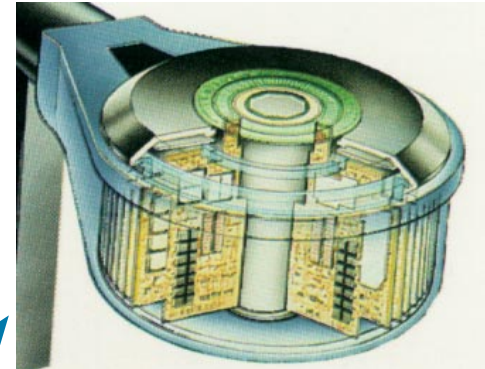
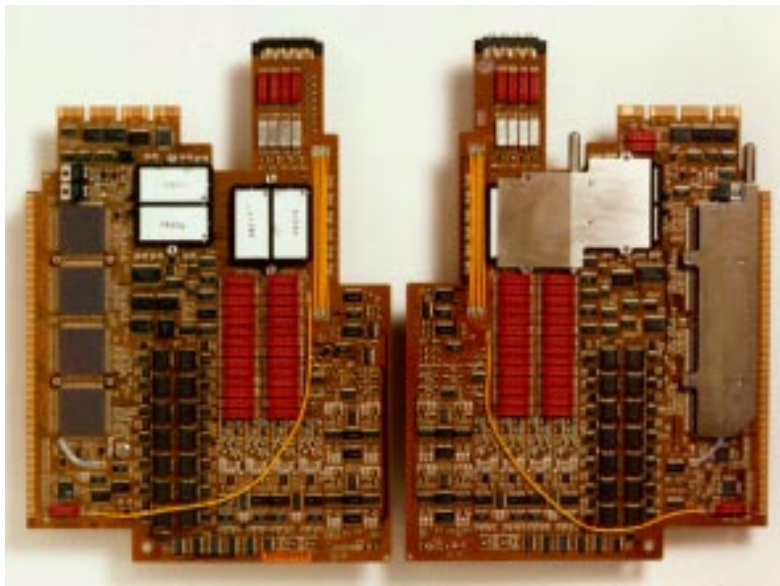
# Fixturing - The Real Issue

- **Tool Automation**
- **Setup Time is significant**
- **Multiple Prober Configurations**
  - Loading
  - Alignment
  - Probe Card
- **Tester Form Factors**

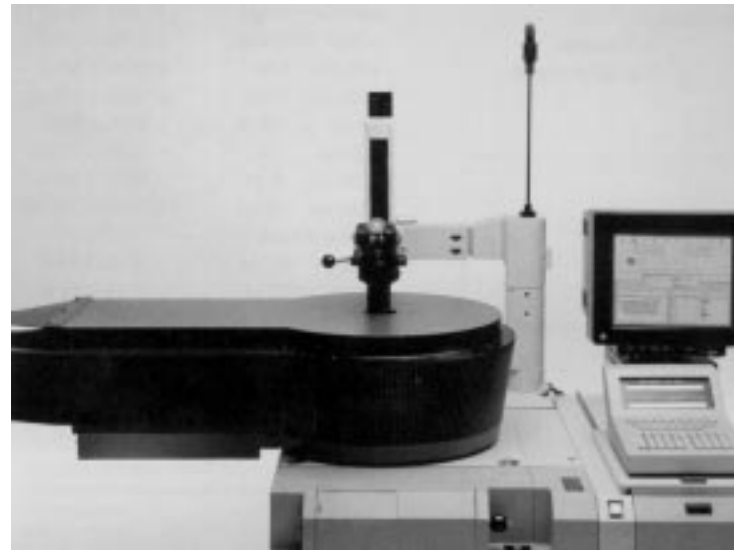
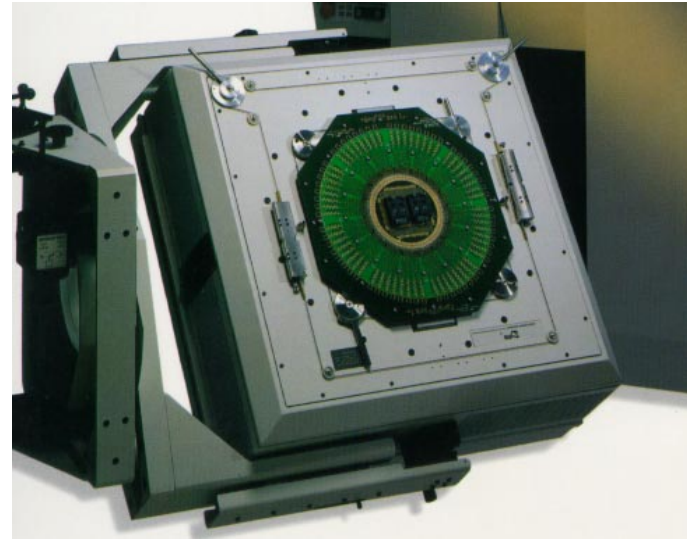


# Tester Design

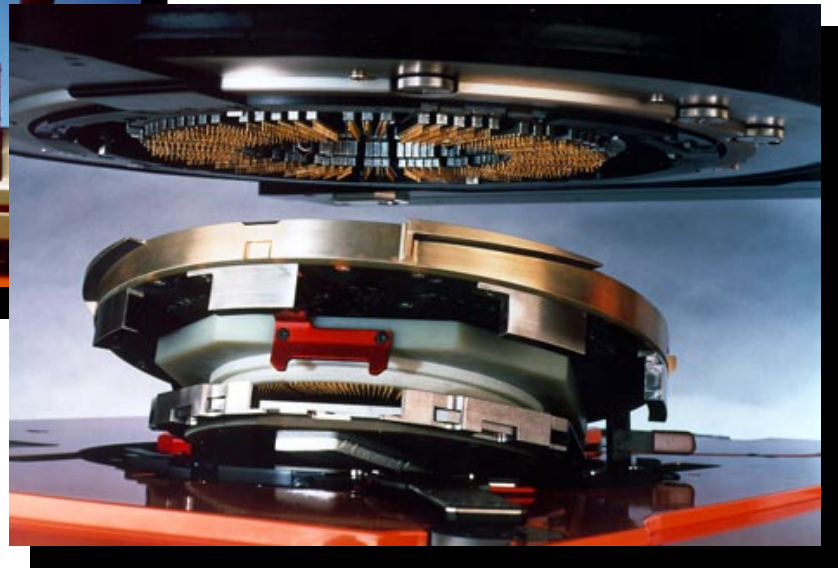
*From the Inside -> Out*



# Tester Form Factors

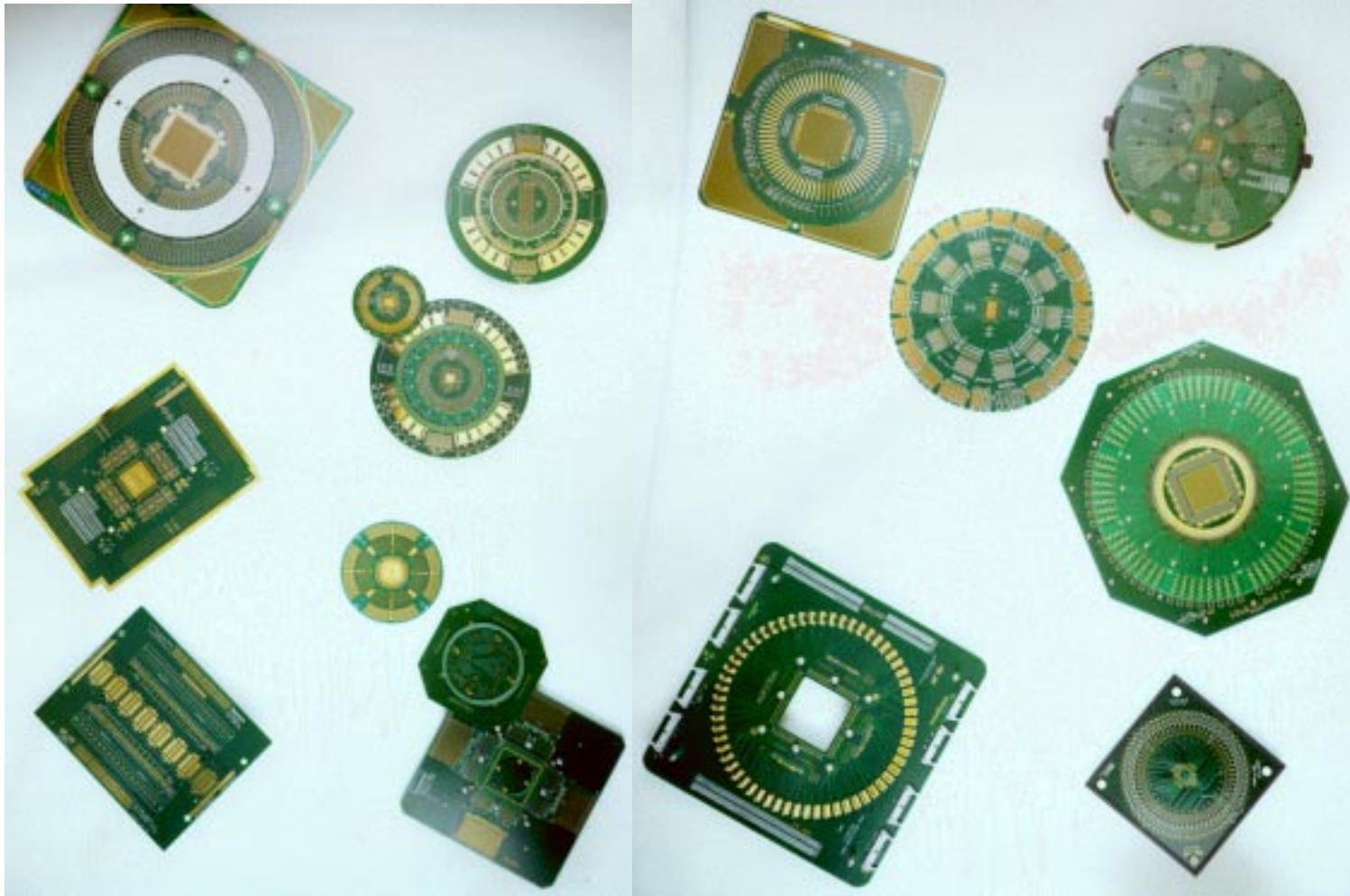


# Interface Variations

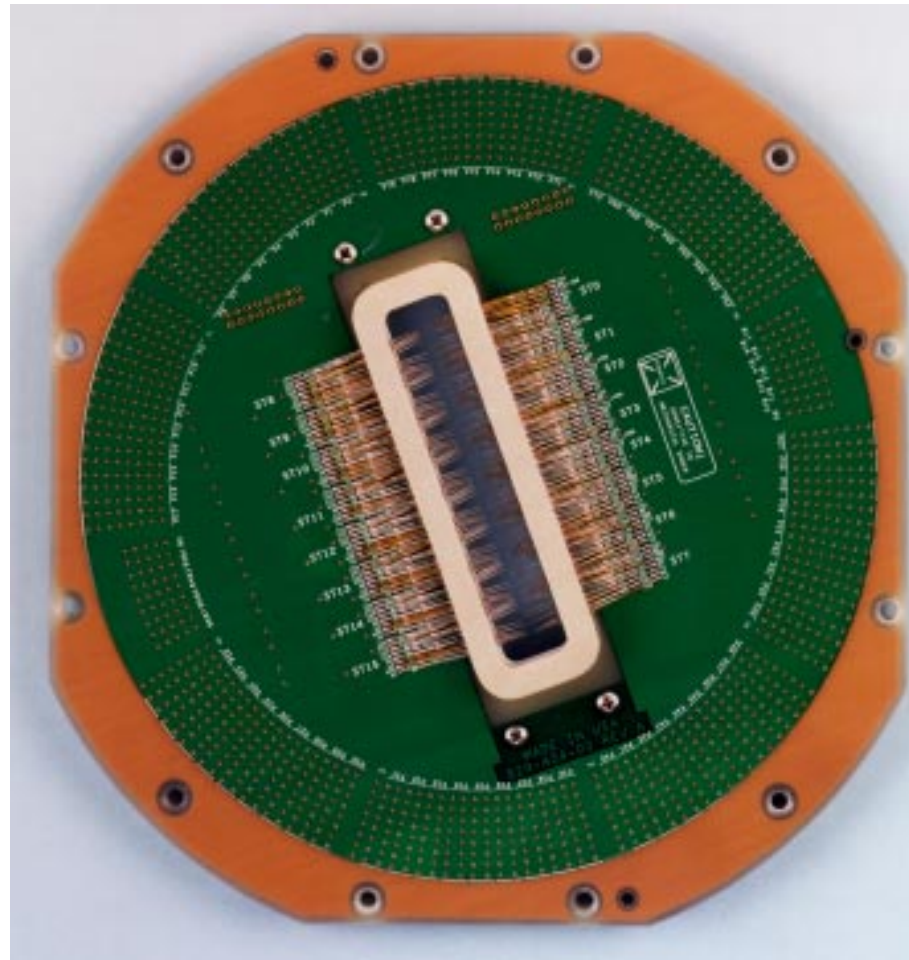




# Interface Proliferation



# Probe Card Complexity



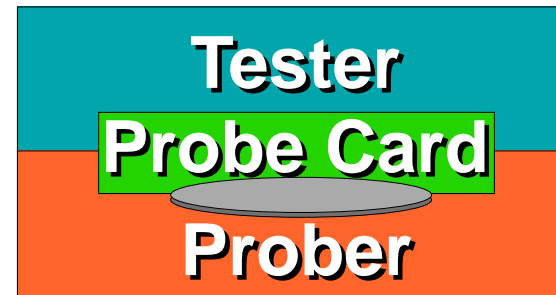
**EPICenter**

**Electroglas  
Probing  
Integration  
Center**





**EPICenter**



## The Vision

*“To be the center of excellence for integration of the prober, probe card and tester technologies.”*



## **EPICenter**

# **What is the EPI Center?**

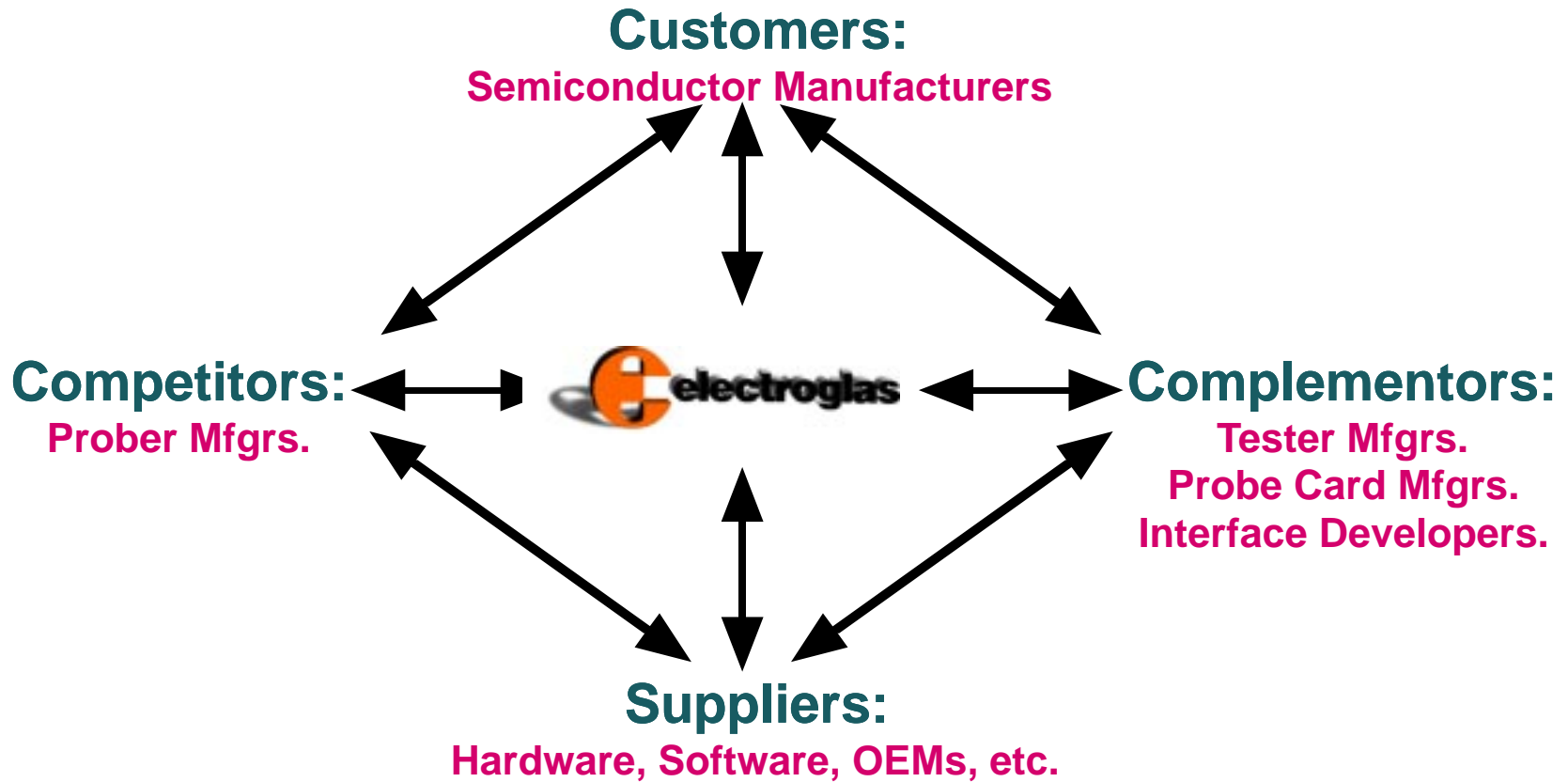
## ***Electroglas Probing Integration Center***

- **Is an Industry resource sponsored by Electroglas and Partners where:**
  - Partners can fully integrate, optimize and test combined probe solutions prior to delivery to customers.
  - New Probe technologies can be characterized.
  - Customers can see & evaluate standard state-of-the-art wafer probe systems.
  - Public domain information can be shared on probe technology.
- **Is not:**
  - A way to gain or lose proprietary intellectual property.
  - Customer specific problem solving



# EPICenter

## The Concept



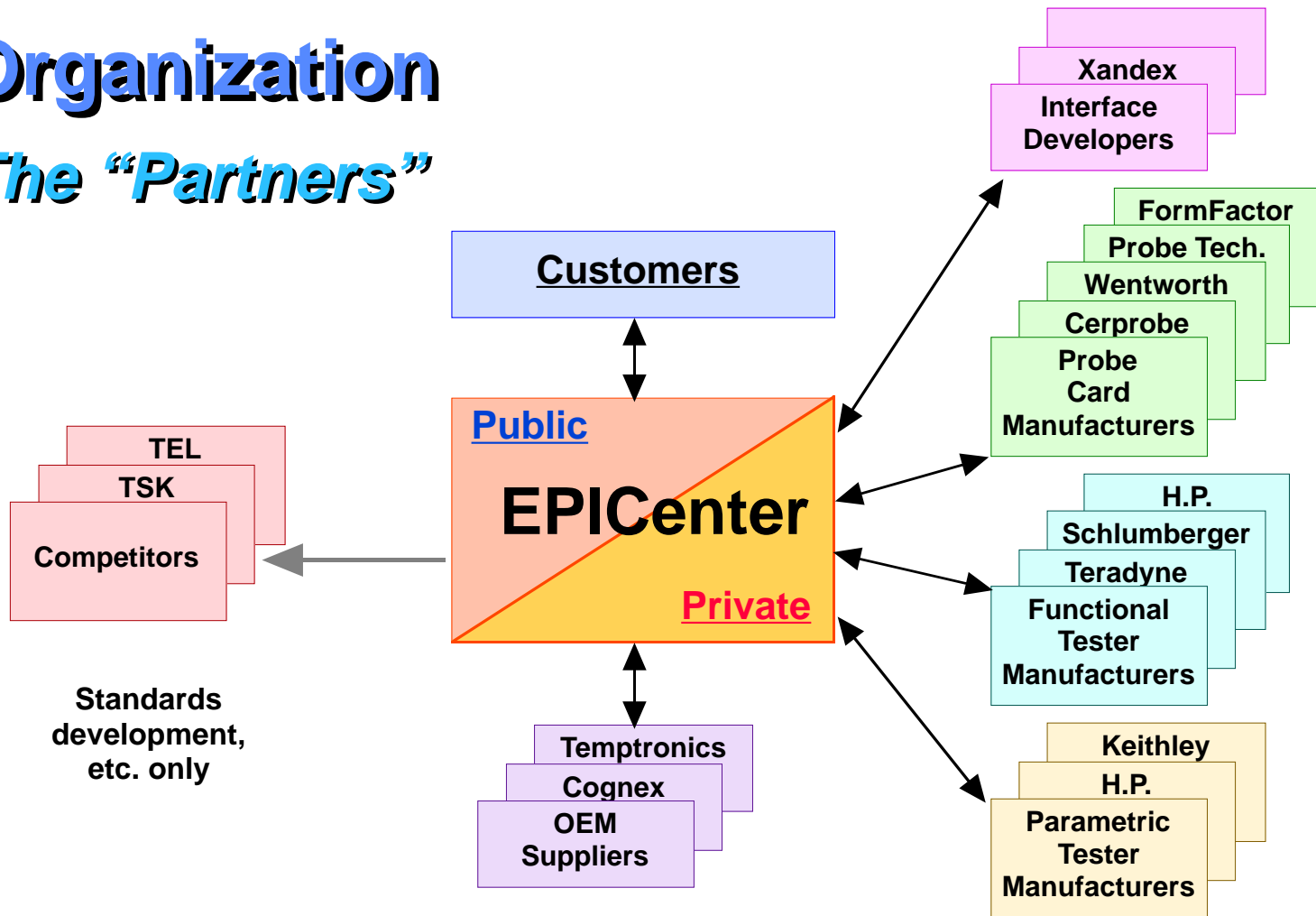
source: "Co-opetition" - Brandenburger & Nalebuff



# EPICenter

## Organization

### The "Partners"



## **EPICenter**

### **The Partners**

- **Keithley Instruments (Parametric Testers)**
- **Hewlett Packard (Para. and Functional Testers)**
- **Teradyne (Functional Testers)**
- **Schlumberger (Functional Testers)**
- **Cerprobe (Probe Cards)**
- **Wentworth (Probe Cards)**
- **Probe Technology (Probe Cards)**
- **FormFactor (Probe Cards)**
- **Xandex (Probe Products)**
- **Temptronic (Thermal Systems)**



# EPICenter

## The Benefits

### *The Customer*

- Turnkey solutions upon delivery.
- Reduced integration costs.
- Reduced time to volume.
- Optimized performance:
  - Mechanical Setup
  - Electrical Setup
  - Probing Process
  - Throughput / Productivity



# **EPICenter**

## **Status**

### ***Phase 1 - Completed***

- **Confirm EGLS Commitment**
- **Sign up Initial Partners**
- **Press Release Announcement**

### ***Phase 2 - Started***

- **Commence Staffing**
- **Set-up Facility**
- **Establish Website**
- **Initiate First Integration Project**



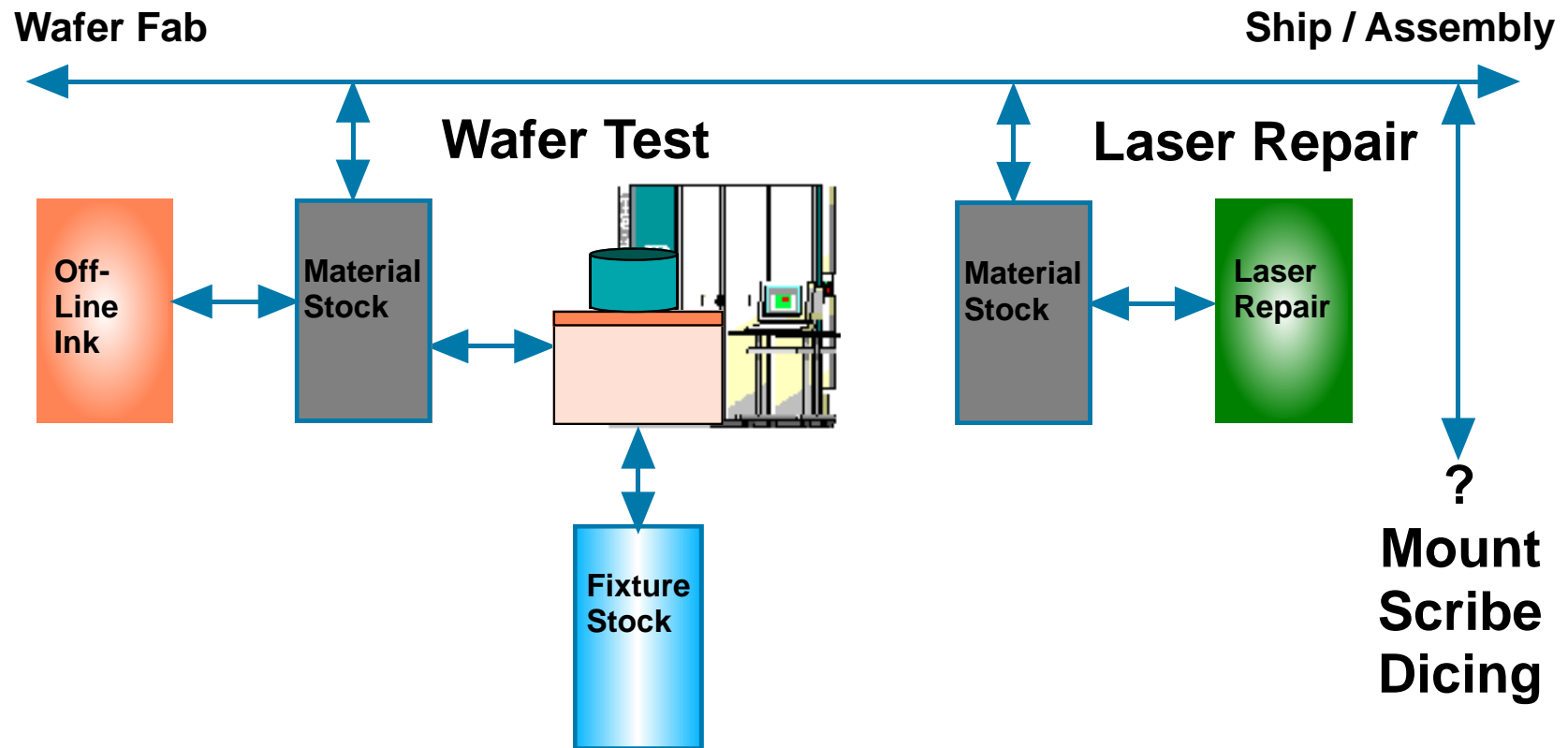
# Automation Responsibilities

- **“Inter-Bay”**  
Any Automation Company
- **“Intra-Bay”**  
Any Automation Company
- **“Tool Automation”**
  - Material Handling    - Prober Companies
  - Fixturing setup        - Prober / Tester / Probe Card Companies



# Wafer Probe

## *A Look Forward....*





**When can we  
turn out the  
lights at  
Probe?**

*Ron Leckie*

